



제 31회 한국반도체학술대회

The 31st Korean Conference on Semiconductors

2024년 1월 24일(수)-26일(금) | 경주화백컨벤션센터(HICO)

2024년 1월 25일(목), 09:00-10:45

Room J(204), 2층

A. Interconnect & Package 분과

[TJ1-A] Emerging Interconnect

좌장: 김병준 교수(한국공학대학교), 주지호 박사(한국전자통신연구원)

TJ1-A-1 09:00-09:15	나노 초 레이저 어닐링을 이용한 비아 플러그의 결정립 크기 증가 정재중 ¹ , 박영근 ¹ , 백용구 ¹ , 김희태 ¹ , 김동빈 ¹ , 김환욱 ² , 조병진 ¹ ¹ 한국과학기술원 전기 및 전자공학부, ² 한국기초과학지원연구원 소재분석연구부
TJ1-A-2 09:15-09:30	Atomic Layer Deposition of RuO ₂ for a Diffusion Barrier in Ru-interconnects Minsu Kim ¹ , Youn-Hye Kim ² , Ki-Seok An ³ , and Soo-Hyun Kim ⁴ ¹ Kyonggi University, ² Yeungnam University, ³ KRICT, ⁴ UNIST
TJ1-A-3 09:30-09:45	Electromigration Reliability of Barrierless Ruthenium and Molybdenum for Sub-10 nm Interconnection Jungkyun Kim, Hakseung Rhee, and Kyung Min Kim KAIST
TJ1-A-4 09:45-10:00	Reduced Size Effect of Resistivity in Cobalt-Palladium (CoPd) Alloys for Advanced Interconnection Applications Hyeong Jun Kim ¹ , Kiyong Lee ² , Tae Won Jeong ³ , Keon Wook Shin ³ , Sang Won Kim ³ , and Changhwan Choi ¹ ¹ Division of Materials Science and Engineering, Hanyang University, ² Department of Materials Science and Engineering, Hongik University, ³ SAIT
TJ1-A-5 10:00-10:15	Selective Deposition of ALD Barrier Metal for Extremely Advanced Cu Interconnect 김기현, 장준기, 박경필, 박치범, 박은영, 이재호, 정은지, 박두환, 김진, 김락환, 하태홍, 안정훈, 이종호 Foundry Business, Samsung Electronics Co., Ltd.
초청발표 TJ1-A-6 10:15-10:45	Improving Mechanical-electrical Reliability of Cu Interconnects based on the Microstructure Analysis Seongi Lee ¹ , Jun Hyeok Hyun ² , and So-Yeon Lee ² ¹ Seoul National University, ² Kumoh National Institute of Technology